### Express recovery diode Reverse Voltage50V-600v Forward current-8A

#### Features

Glass passivated chip

High surge current capability

Ldeal for surface mounted applications

Low power loss, high efficiency

Plastic Case Material has UL Flammability

#### Mechanical Data

Package: SMC

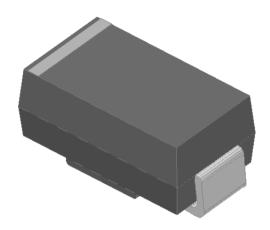
Terminals:Tin Plated leads, solderable per

Mil-STD-750 Method 2026

Polarity: As marked

Molding compound meets UL 94 V-0 flammability rating,

**ROHS-compliant** 





#### Maximum Ratings (Ta=25℃ Unless otherwise specified)

Time Niveskay	CVMDO	ES8A THRU ES8J					
Type Number	SYMBOL	Α	В	D	G	J	Umit
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	V
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	200	400	600	V
Maximum Average Forward Rectified Current at	IO <sub>(AV)</sub>			8.0			Α
Peak Forward Surge Current 8.3ms Single half-sine-wave superimposed on rated load(JEDEC Method) on rated	IFSM	180.0			А		
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25 ℃	ii Giii	360.0			Α		
Current squared time @1ms≤t8.3≤ms Tj=25℃,Rating of per diode	l <sup>2</sup> t	134.5			A <sup>2</sup> S		
Maximum Forward Voltage at 8A DC	$V_{FM}$		0.95		1.3	1.7	V
Maximum Reverse Current TA = 25℃	IR -			5.0			uA
at Rated DC Blocking Voltage TA = 125℃	IK	100.0			uA		
Maximum reverse recovery time	Trr			35.0			ns
Typical Thermal Resistance Between junction and	$R_{QJa}$			48.0			°C/W
Operating Junction Temperature Range	T <sub>J</sub>		-	-55to+15	0		$^{\circ}$
Storage Temperature Range	T <sub>STG</sub>		-	-55to+15	0		$^{\circ}$

FIG. 1MAXIMUM AVERAGE FORWARD CURRENT DERATING

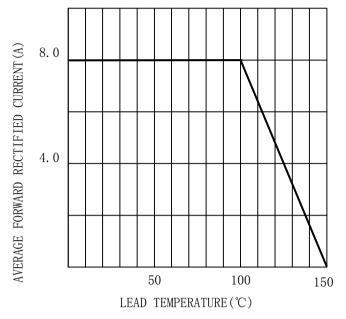


FIG. 2TYPICAL FORWARD CHARACTERISTICS

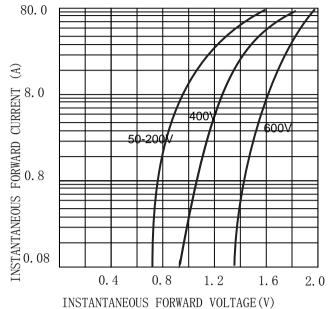


FIG. 3MAXIMUM NON-REPEITIVE SURGE CURRENT

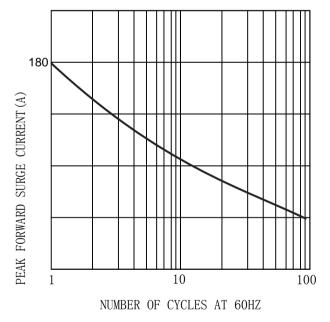
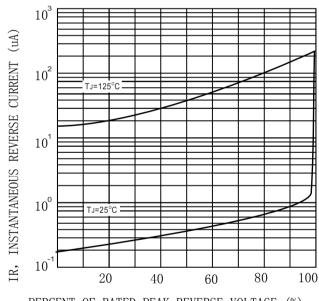


FIG. 4 TYPICAL REVERSE CHARACTERISTICS (per element)



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

### **MARKING INFORMATION**



Signal = Logo

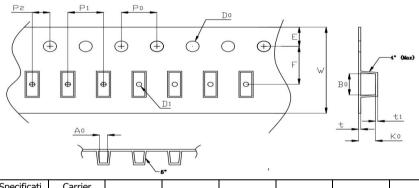
\*\*\*\* = Date Code Marking

ES\*\* = Marking Code

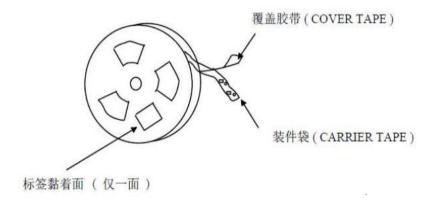
Print according to customer request

### **PACKING REQUIRMENTS**

Carrier tape packing

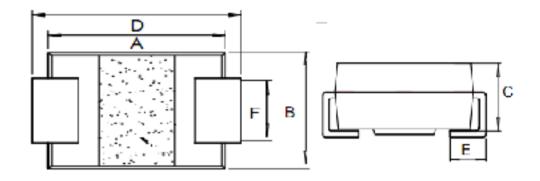


Specificati ons	Carrier tape type	Ao	Во	Ко	Ро	W	t	Exiplain
SMC	Anti-static	6.05±0.1	8.31±0.1	2.54±0.1	3.98±0.05	15.95±0.05	0.23±0.02	



	DEVICE TYPE	Tape width	'Reel				
			Q'TY/REEL (pcs)	BOX/CAR TOON	Q'TY/REEL (pcs)		
	SMC	13.3	3000	T/R	3000		

### Outline Dimensions



SMC						
DTM	INC	HES	MM			
DIM	MIN	MAX	MIN	MAX		
A	0.26	0. 28	6.6	7. 1		
В	0.22	0. 24	5. 5	6. 2		
С	0.08	0.10	2	2.6		
D	0.30	0.32	7. 7	8.2		
Е	/	0.06	/	1.5		
F	0.11	0. 13	2.9	3. 2		



### Important Statements and disclaimers.

Do not copy or modify file information without permission.

Xumao Micro reserves the right to modify this document and its products.

Specifications are available without prior notice. Customer shall obtain and confirm the latest product information and specifications prior to final design, purchase or use.

Xumao Micro does not assume any implied warranties, including warranties of fitness for special purposes, non-infringement and merchantability.

The products shown here are not designed and licensed for demanding equipment at a level of reliability or for human life and any life-saving related applications or life-sustaining, such as medical devices, transportation equipment, aerospace machinery, and so on. Customers who use or sell these products for such applications do so at their own risk.

As Xumao Micro uses batch number as tracking benchmark, please provide batch number for tracking in case of exception.